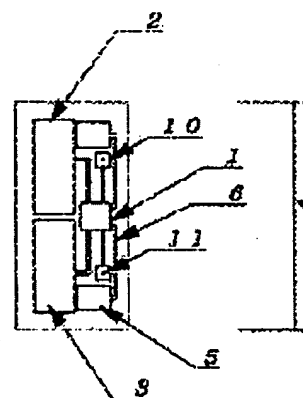


SUBSTRATE FOR NON-CONTACT IC CARD AND THE NON-CONTACT IC CARD

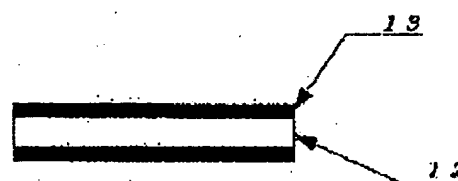
Patent number: JP2002140672
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Inventor: SAKATA NAOYUKI; KOBAYASHI KAZUO
Applicant: TOPPAN PRINTING CO LTD
Classification:
- international: G06K19/07; B42D15/10; G06K19/077
- european:
Application number: JP20000334252 20001101
Priority number(s): JP20000334252 20001101

Abstract of JP2002140672

PROBLEM TO BE SOLVED: To provide a non-contact IC card substrate loaded with capacitors allowed to be formed on a small area, having thickness thinner than an IC chip and high moisture absorption resistance and capable of easily adjusting capacity. **SOLUTION:** Micro-capacitors are used for capacitors 2, 3 to be loaded on a non-contact IC card substrate 4 to be stored in a non-contact IC card base material.



(a)



(b)

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